

Features

- ◆ low Capacitance 15pF
- ◆ Low Clamping Voltage
- ◆ Small Body Outline Dimensions: 0.039"×0.024"
(1.0 mm×0.60 mm)
- ◆ Low Body Height: 0.019"(0.5 mm)
- ◆ Stand-off Voltage: 24V
- ◆ Low Leakage
- ◆ Response Time is Typically < 1 ns
- ◆ IEC61000-4-2 Level 4 ESD Protection for data lines
- ◆ These are Pb-Free Devices



DFN1006-2L



Applications

- ◆ 10/100/1000 Mbits/s Ethernet
- ◆ FireWire
- ◆ Display ports
- ◆ MDDI ports
- ◆ Digital Visual Interface (DVI)
- ◆ Cellular handsets & accessories
- ◆ Computer and peripherals

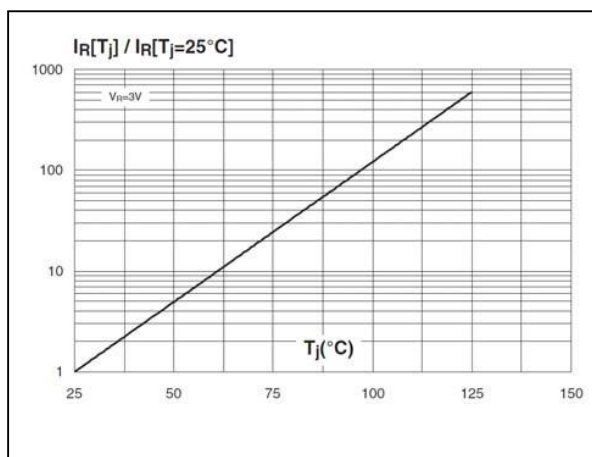
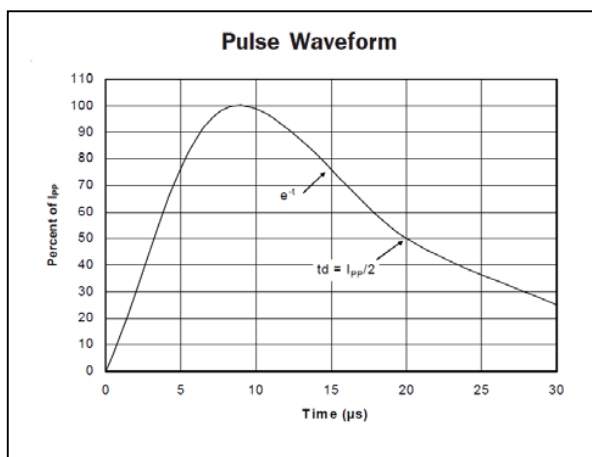
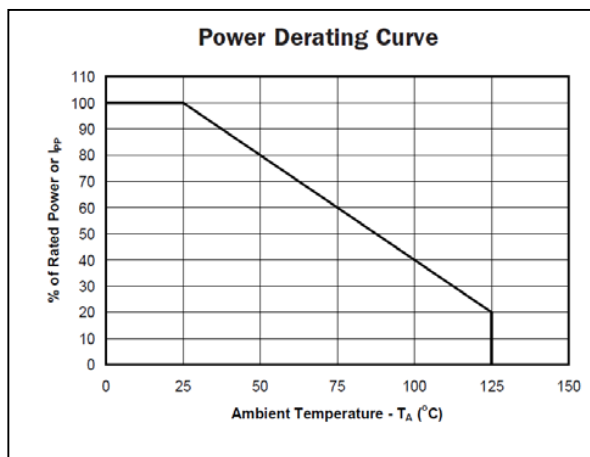
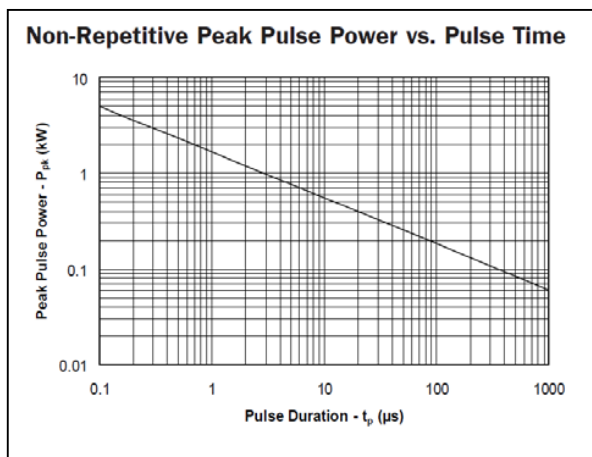
Maximum Rating @ Ta=25°C unless otherwise specified

Symbol	Parameter		Ratings	Units
ESD	IEC 61000-4-2 (HBM-ESD)	Contact	15	KV
		Air	25	
T _L	Lead Soldering Temperature		260(10sec.)	°C
T _J	Operating Temperature		-55 to +125	°C
T _{STG}	Storage Temperature		-55 to +150	°C

Electrical Characteristics@ Ta=25°C unless otherwise

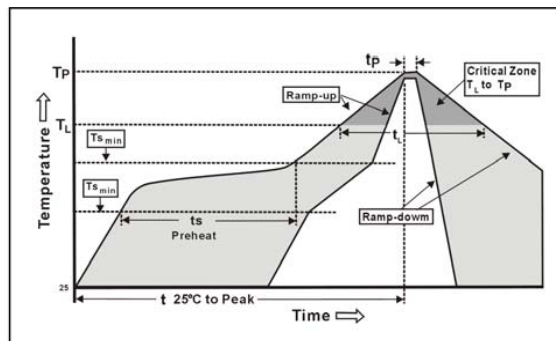
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{RWM}	Reverse Working Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1mA$,	26.7		31.8	V
I_R	Reverse Leakage Current	$V_{RWM} = 24V$			1	μA
V_C	Clamping Voltage	$I_{PP} = 1A$, $t_p = 8/20\mu s$			44	V
		$I_{PP} = 3A$, $t_p = 8/20\mu s$			64	V
C_J	Junction Capacitance	$V_R = 0V$, $f = 1MHz$			15	pF

Typical Characteristics@ Ta=25°C unless otherwise specified



Soldering Parameters

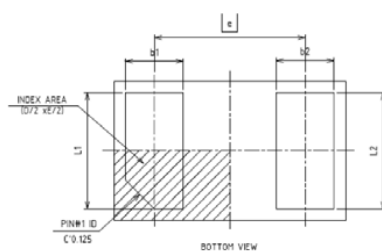
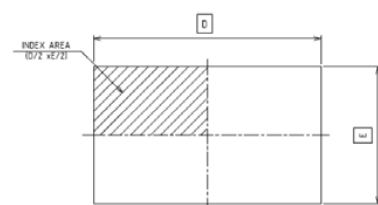
Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(Min)}$)	150°C
	- Temperature Max ($T_{s(Max)}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{s(Max)}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_l)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Package Outline

Plastic surface mounted package

DFN 1006-2L



Symbol	Dimensions in mm		
	Min	Nom	Max
A	0.450	0.500	0.550
A1	0.000	0.002	0.050
D	0.950	1.000	1.050
E	0.550	0.600	0.650
e		0.650	
b1	0.200	0.250	0.300
b2	0.200	0.250	0.300
L1	0.450	0.500	0.550
L2	0.450	0.500	0.550

Soldering Footprint

